

F1 an interposer having a die attach surface and an external surface opposite of the die attach surface disposed in between the semiconductor die and the at least one external terminal, the interposer having at least one electrically conductive interconnect electrically coupling the at least one bond pad of the semiconductor die positioned adjacent to the die attach surface to the at least external terminal positioned adjacent to the external surface, the interposer being formed of an organic substrate or a polyimide substrate; and

a plurality of elongated strips of compliant adhesive film, each strip having a first length and a second length perpendicular to the first length, the first length being substantially greater than the second length, the strips extending substantially the entire distance between the first pair of opposed lateral edges and disposed between the semiconductor die and the interposer the strips further including a compliant carrier layer having a pair of opposing surfaces with a first adhesive layer disposed on a first surface of the opposing surfaces of the carrier layer to adhere the ~~semiconductor die~~ ^{carrier layer} to the die attach surface of the interposer, and a second adhesive layer disposed on a second surface of the opposing surfaces of the carrier layer to adhere the carrier layer to the die.

SUB H2 11. (Three Times Amended) A device package assembly for a semiconductor die being constructed from a process comprising:

F2 laminating a plurality of strips of compliant adhesive film to an interposer having at least one electrically conductive interconnect, the interposer being formed of an organic substrate or a polyimide substrate and further having a die attach surface to which the semiconductor die is attached, and an external surface opposite of the die attach surface;

attaching to the interposer the semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated, the die having first and second pairs of lateral edges, the strips of compliant adhesive film having a first length and a second length perpendicular to the first length, the first length being substantially greater than the second length, the strips extending substantially the entire distance between the first pair of opposed lateral edges, the strips further including a compliant carrier layer having a pair of opposing surfaces with a first adhesive layer disposed on a first surface of the opposing surfaces of the carrier layer to adhere the ~~semiconductor die~~ ^{carrier layer} to the die attach surface of the

interposer, and a second adhesive layer disposed on a second surface of the opposing surfaces of the carrier layer to adhere the carrier layer to the die; and

bonding the at least one electrically conductive interconnect to the at least one electrically conductive bond pad.

38. (Twice Amended) A semiconductor device package, comprising:

a semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated, the die having first and second pairs of lateral edges;

an interposer having a die attach surface and at least one electrically conductive interconnect electrically coupled to at least one bond pad of the semiconductor die, the interposer being formed of an organic substrate or a polyimide substrate; and

a plurality of elongated strips of compliant adhesive film, each strip having a first length and a second length perpendicular to the first length, the first length being substantially greater than the second length, the strips extending substantially the entire distance between the first pair of opposed lateral edges between the die attach surface and the semiconductor die the strips further including a compliant carrier layer having a pair of opposing surfaces with a first adhesive layer disposed on a first surface of the opposing surfaces of the carrier layer to adhere the carrier layer to the die attach surface of the interposer, and a second adhesive layer disposed on a second surface of the opposing surfaces of the carrier layer to adhere the carrier layer to the die.

42. (Three Times Amended) A semiconductor device package, comprising:

a semiconductor die having a first surface on which at least one electrically conductive bond pad is fabricated, the die having first and second pairs of lateral edges;

an interposer having a die attach surface and at least one electrically conductive interconnect electrically coupled to at least one bond pad of the semiconductor die, the interposer being formed of an organic substrate or a polyimide substrate; and

a plurality of elongated strips of compliant adhesive film, each strip having a first length and a second length perpendicular to the first length, the first length being substantially

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 greater than the second length, the strips extending substantially the entire distance between the first pair of opposed lateral edges between the die attach surface and the semiconductor die to adhere the semiconductor die to the die attach surface of the interposer, the strips of compliant adhesive film further including a compliant carrier layer having a pair of opposing surfaces with a first adhesive layer disposed on a first surface of the opposing surfaces of the carrier layer to adhere the carrier layer to the die attach surface of the interposer, and a second adhesive layer disposed on a second surface of the opposing surfaces of the carrier layer to adhere the carrier layer to the die.

Please add new claims 50-53 as follows:

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 --50. (New) The semiconductor device package of claim 1, wherein the carrier layer is further comprised of multiple layers.

51. (New) The device package assembly process of claim 11, wherein the carrier layer is further comprised of multiple layers.

52. (New) The semiconductor device package of claim 38, wherein the carrier layer is further comprised of multiple layers.

53. (New) The semiconductor device package of claim 42, wherein the carrier layer is further comprised of multiple layers. --

REMARKS

Claims 1-3, 15, 17, 18 and 38-45 are pending in the application. In the Office Action dated April 29, 2002, the Examiner rejected claims 10 and 44 under 35 U.S.C. § 112, first paragraph, because the specification, while being enabling for parallel strips of adhesive film, does not reasonably provide enablement for strips positioned at right angles with respect to each